WHAT IS CLAIMED IS:

1. A method for creating a cross section of at least one feature located on a substrate, the method comprising:

coating the feature with a layer of contrast enhancing material;

recoating the feature with a second material different from the contrast enhancing material, the second material having substantially similar milling characteristics as the feature; and

milling the feature.

2. The method of claim 1, wherein the feature comprises resist material.

3. The method of claim 1, wherein the feature comprises dielectric material.

4. The method of claim 1, wherein the feature comprises conducting material.

5. The method of claim 1, wherein the layer of contrast enhancing material comprises a thickness of about 25-50 angstroms.

6. The method of claim 1, wherein coating the feature with the layer of contrast enhancing material comprises utilizing an ion beam tool to deposit the contrast enhancing material.

7. The method of claim 1, wherein recoating the feature comprises utilizing a spin coat machine to recoat the feature with the second material.

8. The method of claim 7, further comprising spinning the substrate at a speed of less than about 1000 rpm.

9. The method of claim 1, wherein milling the feature comprises utilizing an ion beam to mill the feature.

10. The method of claim 10, wherein milling the feature comprises using a precursor gas.

11. The method of claim 1, further comprising creating an image of the feature.

12. The method of claim 11, wherein creating the image of the feature comprises utilizing a scanning electron microscope to create the image.

13. The method of claim 12, further comprising saving the image of the feature.

14. A method for creating a cross section of at least one feature located on a substrate, the method comprising:

patterning the substrate with the feature, the feature comprising a first resist material;

coating the feature with a layer of conducting material;
recoating the feature with a second resist material; and
milling the feature.

15. The method of claim 14, wherein the conducting material comprises platinum.

16. The method of claim 14, wherein the conducting material comprises gold.

17. The method of claim 14, wherein the first resist material and the second resist material comprise the same material.

18. The method of claim 14, wherein the first resist material and the second resist material comprise different materials having substantially similar milling characteristics.

19. The method of claim 14, further comprising creating an image of the feature.

20. A method for creating a cross section of at least one feature located on a substrate, the method comprising:

patterning the substrate with the feature, the feature comprising a first dielectric material;

coating the feature with a layer of conducting material;
recoating the feature with a second dielectric material; and
milling the feature.

21. The method of claim 20, wherein the conducting material comprises platinum.

22. The method of claim 20, wherein the conducting material comprises gold.

23. The method of claim 20, wherein the first dielectric material and the second dielectric material comprise the same material.

24. The method of claim 20, wherein the first dielectric material and the second dielectric material comprise different materials having substantially similar milling characteristics.

25. The method of claim 20, further comprising creating an image of the feature.

26. A method for creating a cross section of at least one feature located on a substrate, the method comprising:

patterning the substrate with the feature, the feature comprising a first conducting material;

coating the feature with a layer of dielectric material;

recoating the feature with a second conducting material; and

milling the feature.

27. The method of claim 26, wherein the non-conducting material comprises metal oxide.

28. The method of claim 26, further comprising creating an image of the feature.

29. The method of claim 26, wherein the first conducting material and the second conducting material comprise the same material.

30. The method of claim 26, wherein the first conducting material and the second conducting material comprise different materials having substantially similar milling characteristics.